



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



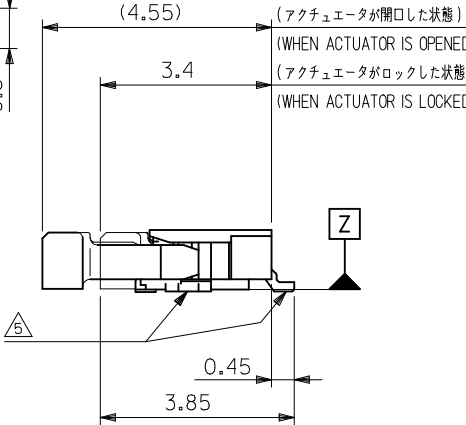
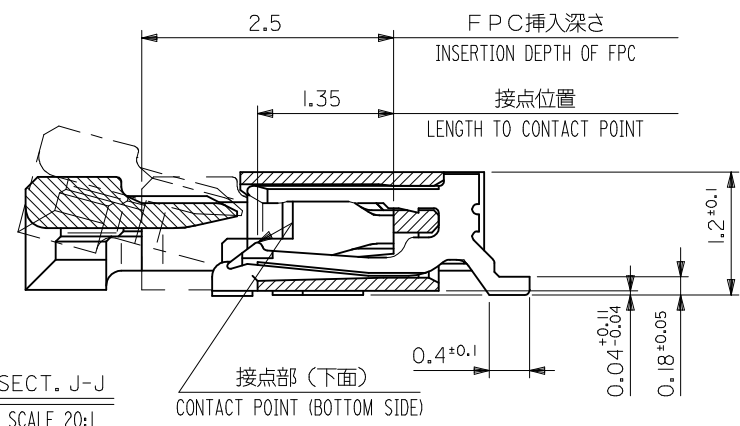
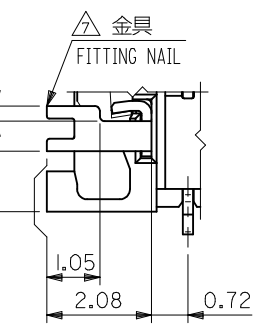
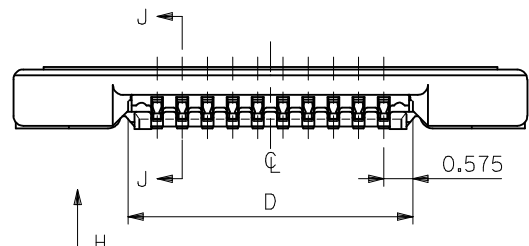
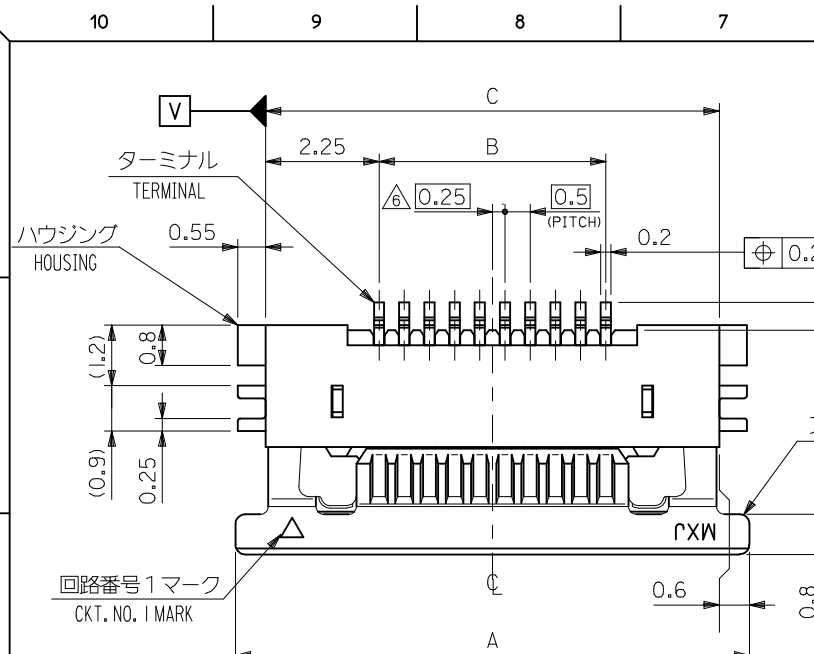
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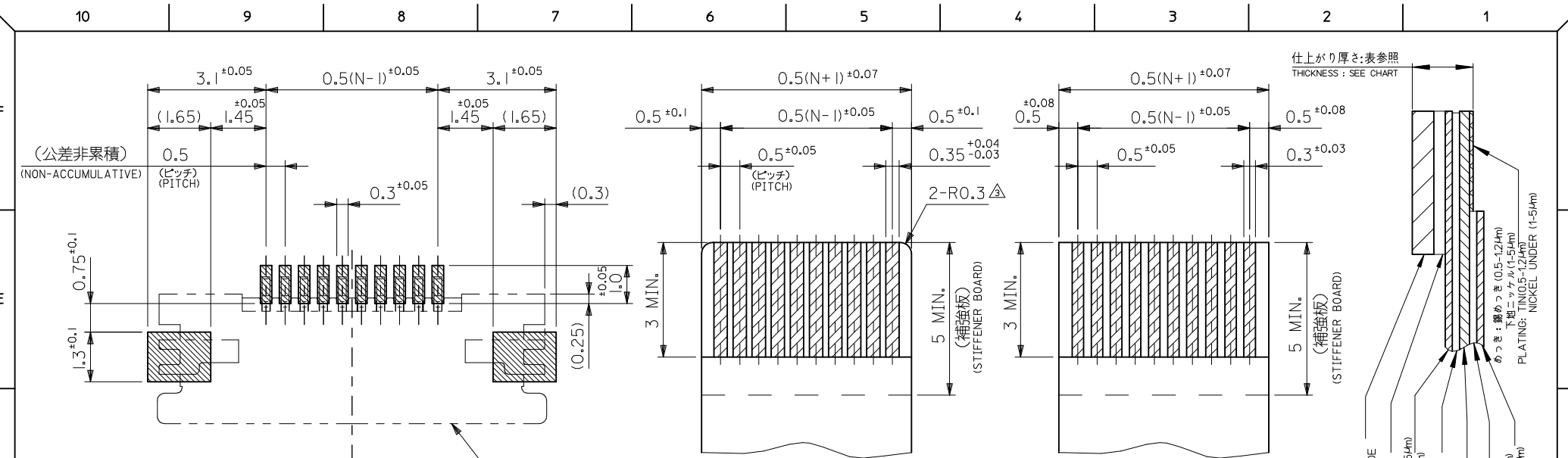
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





0.3 ^{+0.03}	0.28 ^{+0.03}	13.65	17	12.5	18.2	54548-2633	54548-2622	26
		12.65	16	11.5	17.2	54548-2433	54548-2422	24
		11.65	15	10.5	16.2	54548-2233	54548-2222	22
		11.15	14.5	10	15.7	54548-2133	54548-2122	21
		10.65	14	9.5	15.2	54548-2033	54548-2022	20
		10.15	13.5	9	14.7	54548-1933	54548-1922	19
		9.65	13	8.5	14.2	54548-1833	54548-1822	18
		9.15	12.5	8	13.7	54548-1733	54548-1722	17
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		8.15	11.5	7	12.7	54548-1533	54548-1522	15
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	6.15	9.5	5	10.7	54548-1133	54548-1122	11	
	5.65	9	4.5	10.2	54548-1033	54548-1022	10	
	5.15	8.5	4	9.7	54548-0933	54548-0922	9	
	4.65	8	3.5	9.2	54548-0833	54548-0822	8	
	4.15	7.5	3	8.7	54548-0733	54548-0722	7	
	3.65	7	2.5	8.2	54548-0633	54548-0622	6	
	3.15	6.5	2	7.7	54548-0533	54548-0522	5	
	2.65	6.0	1.5	7.2	54548-0433	54548-0422	4	
THICKNESS OF FPC		D	C	B	A	EMBOSSED TAPE ORDER No. オータ番号	製品番号 MATERIAL No.	極数 CIRCUIT

RELEASED EC NO: J2014-0734 DRWN: JASANUMA 2013/12/04 CHKD: KTAKAHASHI 2013/12/04 APPR: YNOGAWA 2014/01/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	MODEL NO. 54548-**22	
	10 UNDER	±0.2	DRAWN BY JASANUMA	DATE 2013/12/04	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT			
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2013/12/04				
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/01/10				
ANGULAR	±3°	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54548-043		SHEET NO. 1 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



参考基板レイアウト
RECOMMENDED P.C.B. BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

コネクタ位置
CONNECTOR POSITION

適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ:表参照)
(THICKNESS:SEE CHART)

- FPC構成推奨仕様
STRUCTURE OF FPC
- 補強板:ポリイミド REINFORCE BOARD: POLYIMIDE
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - ベースフィルム:ポリイミド(25µm) BASE FILM: POLYIMIDE(25µm)
 - 銅箔(35µm) COPPER FOIL (35µm)
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - 銅箔(35µm) COPPER FOIL (35µm)
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - カバーレイ:ポリイミド(25µm) COVER FILM: POLYIMIDE(25µm)
 - めっき:銀(0.5-1.2µm) 下層:ニッケル(1-5µm) PLATING: NICKEL UNDER (1-5µm)

注記 NOTES

1. 使用材料 MATERIAL

- ハウジング : 液晶ホリマー (LCP)、ナチュラル(白色)、ガラス充填、UL94V-0
- HOUSING LIQUID CRYSTAL POLYMER, NATURAL(WHITE), GLASS FILLED, UL-94V0
- アクチュエータ : ポリフェニレンサルファイド(PPS)、黒色ガラス充填、UL94V-0
- ACTUATOR POLYPHENYLENE SULFIDE, BLACK, GLASS FILLED, UL-94V0
- ターミナル : リン青銅 (t=0.2)
- TERMINAL PHOSPHOR BRONZE (t=0.2)
- 金具 : リン青銅 (t=0.2)
- FITTING NAIL PHOSPHOR BRONZE (t=0.2)

- △ソルダーテール半田付け面のスレ量、及び金具半田付け面のスレ量は、基準面 Z に対し上方向 OMAX.、下方向 0.15MAX.とし、相互のパラッキ量は0.1MAX.とする。
- MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0 MAX., LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1MAX.
- △偶数種に適用。 APPLY FOR EVEN CIRCUIT.
- △パターンはくり止め用金具 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
- 8. ELV及びRoHS適合品 ELV AND ROHS COMPLIANT

- FPC/FFCについて ABOUT FPC/FFC
- 打ち抜き方向は導体側から補強板側を推奨します。
導体部については銅箔35µmまたは50µmを推奨します。
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
- FPCについて ABOUT FPC
- 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

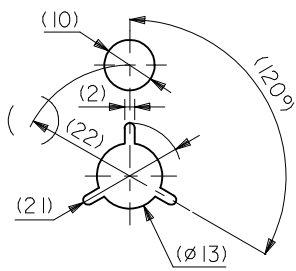
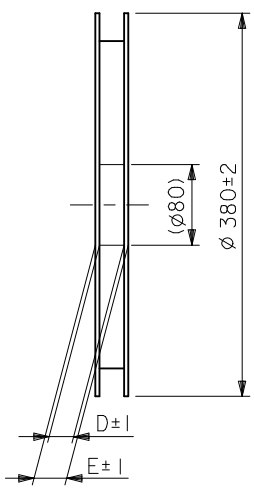
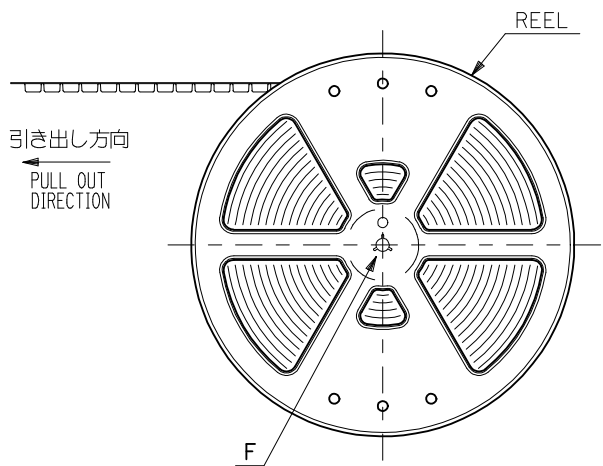
2. めっき仕様 PLATING
- ターミナル TERMINAL
 - 鍍銀ビスマスメッキ(1.0µm以上)
 - 下地:ニッケルメッキ(1.0µm以上)
 - TIN SILVER BISMUTH PLATING (1.0 MICROMETER MINIMUM)
 - UNDER PLATE : NICKEL PLATING (1.0 MICROMETER MINIMUM)
 - 金具 FITTING NAIL
 - 鍍メッキ(1.0µm以上)
 - 下地:ニッケルメッキ(1.0µm以上)
 - TIN PLATING
 - TIN PLATING (1.0 MICROMETER MINIMUM)
 - UNDER PLATE : NICKEL PLATING (1.0 MICROMETER MINIMUM)

- △R0.3はFPCの導体部にかからないこと R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
- 4. エンボステープ梱包時は、アクチュエータがロックした状態とする。 IN THE PACKAGE, ACTUATOR OF PART NO.54548-**22 SHOULD BE LOCKED.

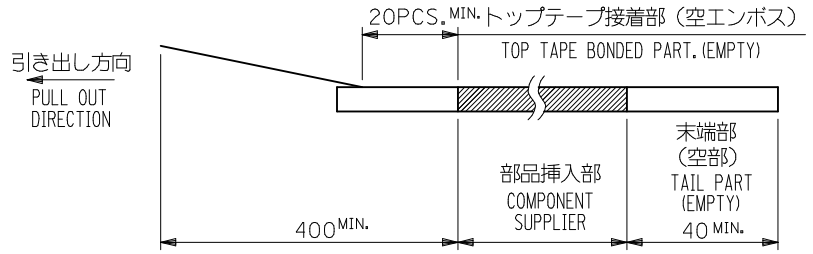
RELEASED EC NO: J2014-0734 DRWN: JASANUMA 2013/12/04 CHKD: KAKAHASHI 2013/12/04 APPR: YNOGAWA 2014/01/10	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE		54548-**22 MODEL No.	
				MM ONLY		---		DESIGN UNITS	
				DRAWN BY DATE		TITLE		METRIC	
				JASANUMA 2013/12/04		0.5 FPC CONN ZIF HSG ASSY FOR SMT RA BTM CONT		THIRD ANGLE PROJECTION	
REV: 0	DESCRIPTION	10 UNDER	±0.2	CHECKED BY DATE	molex				
		10 OVER 30 UNDER	±0.25	KTAKAHASHI 2013/12/04					
		30 OVER	±0.3	APPROVED BY DATE	SD-54548-043		SHEET NO.		
		ANGULAR ±3 °		YNOGAWA 2014/01/10	SEE SHEET 1		2 OF 2		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.					
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

NOTES

- 製品詳細寸法については図面 SD-54548-043 を参照下さい。
RE DETAILED DIMENSION, SEE SD-54548-043
- 梱包数量：3000個/リール
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



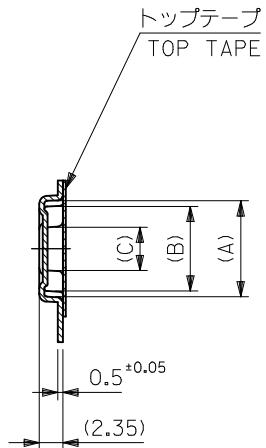
DETAIL F



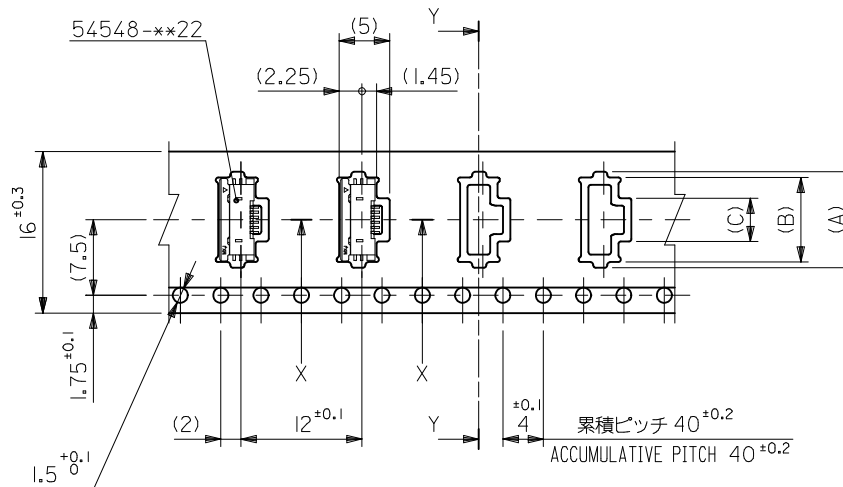
- カバーテープの剥離強度については、IEC60286-3に準拠。
COVER TAPE PEEL FORCE IS DEFINED BY IEC60286-3.
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET, PE, PEF
リール (REEL) : ポリスチレン (P.S) <リサイクル材を含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>
- ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

RELEASED EC NO: J2014-0734 DRWN: JASANUMA 2013/12/04 CHKD: TAKAHASHI 2013/12/04 APPR: YNOGAWA 2014/01/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		54548-**33		MODEL NO.	
	10 UNDER ±0.2		DRAWN BY JASANUMA DATE 2013/12/04		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 OVER 30 UNDER ±0.25		CHECKED BY KTAKAHASHI DATE 2013/12/04		TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY			
	30 OVER ±0.3		APPROVED BY YNOGAWA DATE 2014/01/10					
	ANGULAR ±3 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54548-044 SHEET NO. 1 OF 4			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3						

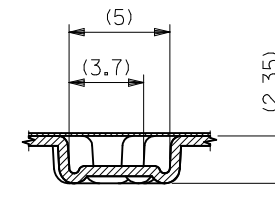
引き出し方向
PULL OUT DIRECTION



SECT. Y-Y



16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE



SECT. X-X

16	21.4	17.4	4.3	8.4	9.5	54548-0633	6
			3.8	7.9	9	54548-0533	5
			3.3	7.4	8.5	54548-0433	4
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	(C)	(B)	(A)	製品番号 MATERIAL No.	極数 CIRCUIT

54548-**33		MODEL NO.	
SCALE 2:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
DRAWN BY JASANUMA		DATE 2013/12/04	
CHECKED BY KTAKAHASHI		DATE 2013/12/04	
APPROVED BY YNOGAWA		DATE 2014/01/10	
MATERIAL NO. SEE CHART		DOCUMENT NO. SD-54548-044	
SIZE A3		SHEET NO. 2 OF 4	

RELEASED EC NO: J2014-0734 DRWN: JASANUMA 2013/12/04 CHKD: KTAKAHASHI 2013/12/04 APPR: YNOGAWA 2014/01/10	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	10 UNDER	±0.2
	10 OVER 30 UNDER	±0.25
	30 OVER	±0.3
	ANGULAR	±3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

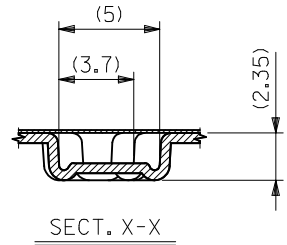
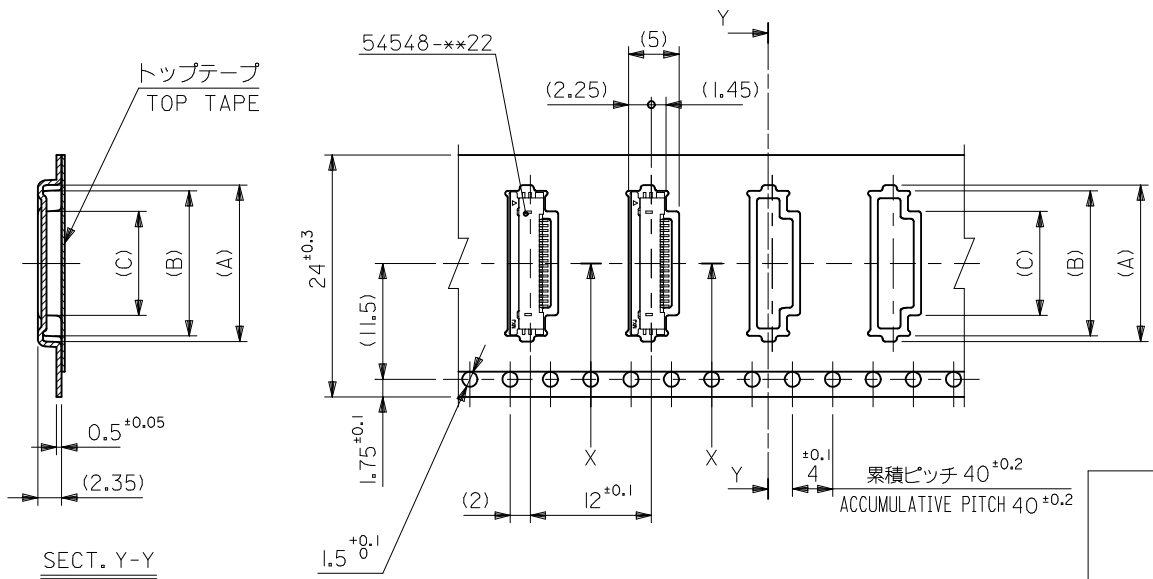
EMBSTP PKG FOR 0.5 FPC
CONN ZIF HSG ASSY

molex

SD-54548-044

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引き出し方向
PULL OUT DIRECTION



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	29.4	25.4	12.3	16.4	17.5	54548-2233	22
			11.8	15.9	17	54548-2133	21
			11.3	15.4	16.5	54548-2033	20
			10.8	14.9	16	54548-1933	19
			10.3	14.4	15.5	54548-1833	18
			9.8	13.9	15	54548-1733	17
			9.3	13.4	14.5	54548-1633	16
			8.8	12.9	14	54548-1533	15
			8.3	12.4	13.5	54548-1433	14
			7.8	11.9	13	54548-1333	13
			7.3	11.4	12.5	54548-1233	12
			6.8	10.9	12	54548-1133	11
			6.3	10.4	11.5	54548-1033	10
5.8	9.9	11	54548-0933	9			
5.3	9.4	10.5	54548-0833	8			
4.8	8.9	10	54548-0733	7			
キャリアテープ幅 CARRIER TAPE WIDTH			(C)	(B)	(A)	製品番号 MATERIAL No.	極数 CIRCUIT

RELEASED EC NO: J2014-0734 DRWN: JASANUMA 2013/12/04 CHKD: TAKAHASHI 2013/12/04 APPR: YNOGAWA 2014/01/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 2:1	DESIGN UNITS METRIC	MODEL NO. 54548-***33
	10 UNDER	±0.2	DRAWN BY JASANUMA	DATE 2013/12/04	TITLE EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY		
	10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2013/12/04			
	30 OVER	±0.3	APPROVED BY YNOGAWA	DATE 2014/01/10	THIRD ANGLE PROJECTION molex DOCUMENT NO. SD-54548-044 SHEET NO. 3 OF 4		
ANGULAR ±3 °		MATERIAL NO. SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

